

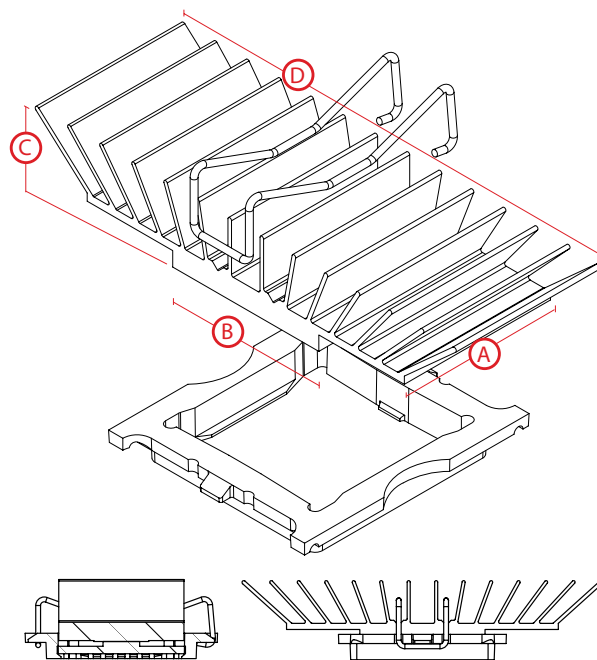


# Custom High Performance Cooling Solutions w/ maxiGRIP™ Attachment

**ATS PART # ATS-59001-C2-R0**

## Features & Benefits

- » Designed for flip-chip processors such as Freescale MPCs
- » maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- » Comes preassembled with high performance, phase changing, thermal interface material



*\*Image above is for illustration purposes only.*

## Thermal Performance

### AIR VELOCITY

FT/MIN

M/S

### THERMAL RESISTANCE

°C/W (UNDUCTED FLOW)

°C/W (DUCTED FLOW)

200

1.0

4.5

3

300

1.5

3.6

400

2.0

3.2

500

2.5

2.9

600

3.0

2.7

700

3.5

2.5

800

4.0

2.4

## Product Details

DIMENSION A

DIMENSION B

DIMENSION C

DIMENSION D

INTERFACE MATERIAL

FINISH

28 mm

45 mm

11 mm

59 mm

SAINT-GOBAIN C1100F

BLACK-ANODIZED

### NOTES:

- 1) Dimension C = heat sink height from bottom of the base to the top of the fin field.
- 2) ATS-59001-C1-R0 is a substitute item available utilizing an equivalent phase change material (Chomerics T766).
- 3) Thermal performance data are provided for reference only. Actual performance may vary by application.
- 4) ATS reserves the right to update or change its products without notice to improve the design or performance.
- 5) Contact ATS to learn about custom options available.



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